

Industrial RJ45 Mag Jack

TE Internal #: 2337992-4

RJ45 with Integrated Magnetics Connector, Single Port, 1 x 1, Jack, Shielded, Cat 5, Standard - Latch Down, 8 Position, Industrial RJ45

Mag Jack

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Connectors > Modular Jacks & Plugs > RJ45 Connectors











Modular Jack & Plug Interface Type: RJ45 with Integrated Magnetics

Port Configuration: Single Port
Port Matrix Configuration: 1 x 1

Modular Jacks & Plugs Products: RJ Type Jacks & Plugs

Connector Contact Density: Standard

Features

Product Type Features

Modular Jack & Plug Interface Type	RJ45 with Integrated Magnetics
Modular Jacks & Plugs Products	RJ Type Jacks & Plugs
Modular Connector Style	Jack
Grounding Options	PCB and Panel Ground
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of PCB Ground Tabs	2
Panel Ground Location	Top and Side
Number of Panel Ground Tabs	6
Port Configuration	Single Port
Port Matrix Configuration	1 x 1
Connector Contact Density	Standard
Number of Positions	8

8

Number of Loaded Positions



PCB Mount Orientation	Right Angle
Signal Characteristics	
Data Rate	.01 Gb/s, .1 Gb/s
Body Features	
LED Color (Bottom Left)	Green
Insulator Material	LCP
LED Color (Bottom Right)	Yellow
Shield Plating Material	Nickel
Shield Plating Finish	Matte
Shield Material	Brass
PCB Retention Feature Material	LCP
LED Color (Top Right)	None
LED Color (Top Left)	None
PCB Ground Tab Location	3.05 mm[.12 in]
Modular Jack Latch Orientation	Standard - Latch Down
Connector Profile	Standard
Contact Features	
Contact Features Contact Underplating Material	Nickel
	Nickel Matte
Contact Underplating Material	
Contact Underplating Material PCB Contact Termination Area Plating Material Finish	Matte
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material	Matte Tin
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material	Matte Tin Gold (Au)
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Base Material	Matte Tin Gold (Au) Copper Alloy
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Base Material Contact Mating Area Plating Material Thickness	Matte Tin Gold (Au) Copper Alloy
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Base Material Contact Mating Area Plating Material Thickness Termination Features	Matte Tin Gold (Au) Copper Alloy .76 μm[30 μin]
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Base Material Contact Mating Area Plating Material Thickness Termination Features Termination Method to PCB	Matte Tin Gold (Au) Copper Alloy .76 μm[30 μin]
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Base Material Contact Mating Area Plating Material Thickness Termination Features Termination Method to PCB Mechanical Attachment	Matte Tin Gold (Au) Copper Alloy .76 μm[30 μin] Through Hole - Solder
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Base Material Contact Mating Area Plating Material Thickness Termination Features Termination Method to PCB Mechanical Attachment PCB Mount Retention Type	Matte Tin Gold (Au) Copper Alloy .76 μm[30 μin] Through Hole - Solder
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Base Material Contact Mating Area Plating Material Thickness Termination Features Termination Method to PCB Mechanical Attachment PCB Mount Retention Type Housing Features	Matte Tin Gold (Au) Copper Alloy .76 μm[30 μin] Through Hole - Solder Boardlock
Contact Underplating Material PCB Contact Termination Area Plating Material Finish PCB Contact Termination Area Plating Material Contact Mating Area Plating Material Contact Base Material Contact Mating Area Plating Material Thickness Termination Features Termination Method to PCB Mechanical Attachment PCB Mount Retention Type Housing Features Mating Entry Location	Matte Tin Gold (Au) Copper Alloy .76 μm[30 μin] Through Hole - Solder Boardlock Side



Connector Height	13.63 mm[.537 in]
Usage Conditions	
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	
Indicator Type	LED
Shielded	Yes
Industry Standards	
UL Flammability Rating	UL 94V-0
Performance Category	Cat 5
Packaging Features	
Packaging Quantity	80
Packaging Method	Reel
Other	
Shield Panel Ground Type	Shield has bottom panel grounds.

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	有害物质含量符合标准要求 No Restricted Substance(s) Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2025 (250) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits

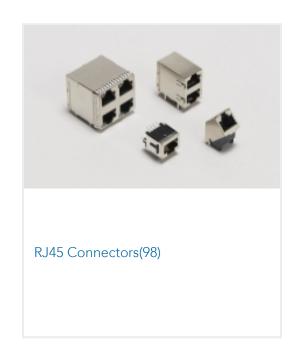


as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Industrial RJ45 Mag Jack



Customers Also Bought















Documents



Product Drawings

RJ45 JACK MAG. POE 10/100 LED 1X1

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2337992-4_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2337992-4_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2337992-4_A.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

ETHERNET JACKS WITH INTEGRATED MAGNETICS AND PoE

English

Product Specifications

Application Specification

English

Agency Approvals

UL

English